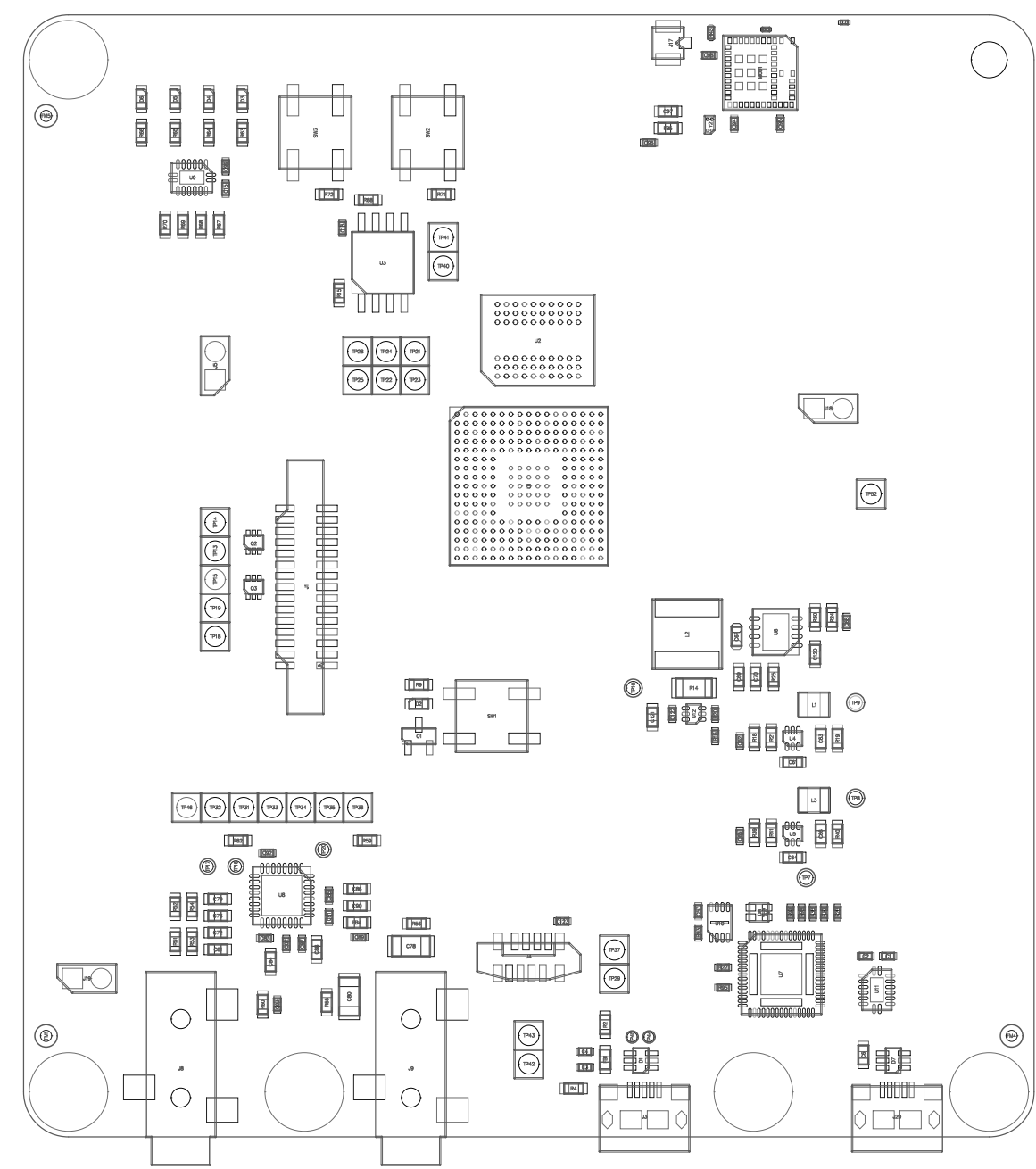
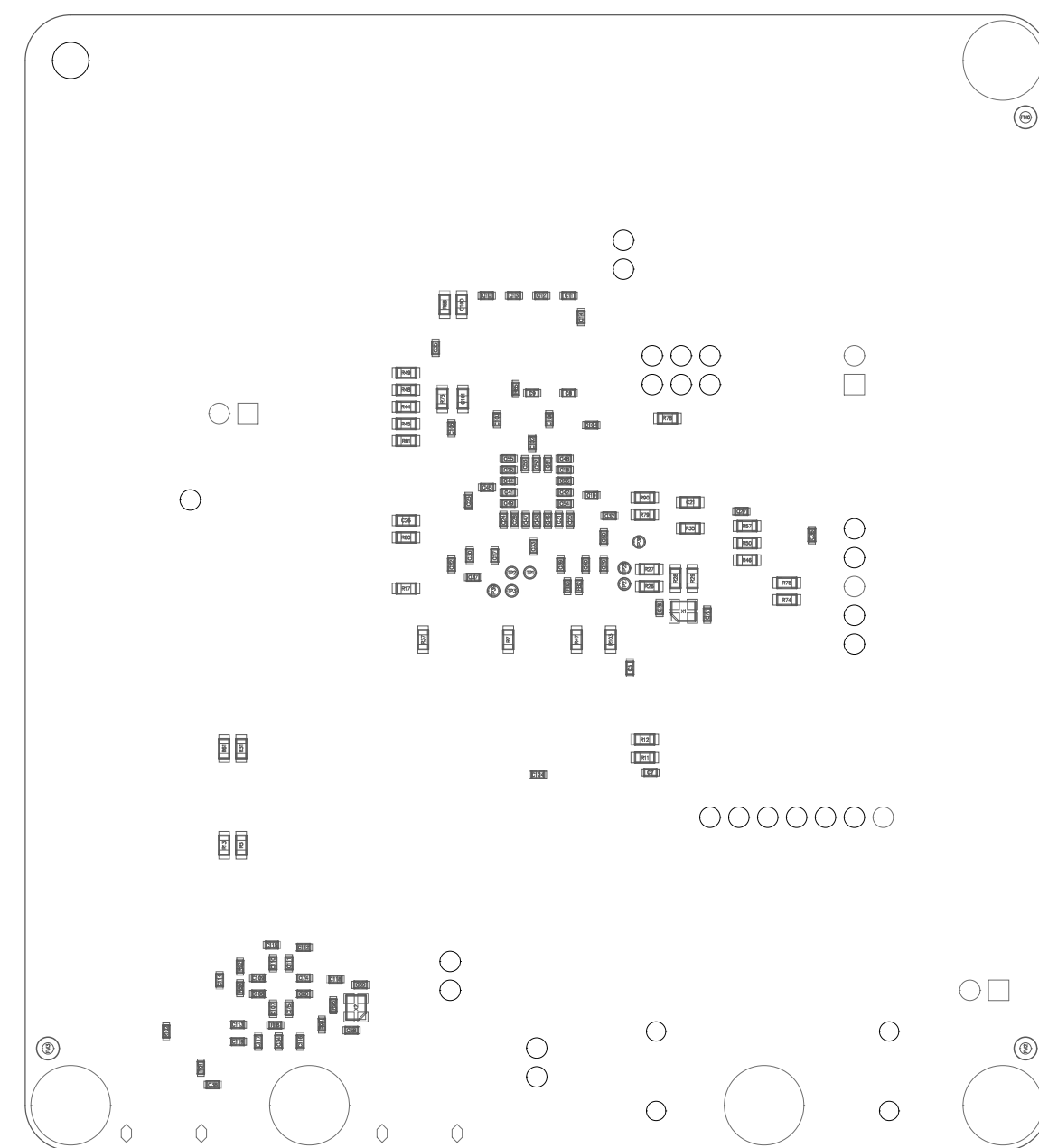


PCB ASSEMBLY INSTRUCTIONS

- 1.) SOLDERPASTE – ROHS/LEAD FREE NO CLEAN SOLDERPASTE.  
PADS HAVE NOT BEEN UNDERSIZED.  
ASSEMBLER SHOULD UNDERSIZE PADS TO SUIT PROCESS.  
SUGGEST 125UM MAX STENCIL THICKNESS.
- 2.) ONLY COMPONENT PINS TO BE SOLDERED SHOULD BE EXPOSED TO SOLDER WAVE.  
ALL OTHER EXPOSED COPPER TO BE MASKED.
- 3.) TWO PIN COMPONENT ORIENTATION:  
POLARISED MOLDED CAPACITORS – PIN 1 IS THE POLARIY MARK PIN (POSITIVE).  
MOLDED DIODES – PIN 1 IS THE POLARITY MARK PIN (CATHODE).
- 4.) ENSURE THROUGH HOLE PINS OF USB CONNECTORS J3 AND J20 ARE SOLDERED IN ADDITION TO SMD PADS.
- 5.) NOTE THAT USB CONNECTORS J3 AND J20 ARE NOT FLAT SO REQUIRE A RELIEF OUTSIDE THE EDGE OF THE BOARD.
- 6.) NOTE MODULE MOD1 IS AN LGA WITH SMALL PADS WHICH REQUIRES ACCURATE PASTE DEPOSITION.  
SEE SILICON LABS APP NOTE AN1223–LGA–MANUFACTURING–GUIDANCE.



JGB0070 = 2V0 = 02/11/2021  
TOP ASSEMBLY



BOTTOM ASSEMBLY